

Amendments to the Specification:

Please replace the paragraph beginning on pg. 38, line 8, with the following rewritten paragraph.

Additional examples of methods and systems for inspecting a semiconductor topography are illustrated in U.S. Patent Nos. 4,247,203 to Levy et al., 4,347,001 to Levy et al., 4,378,159 to Galbraith, 4,448,532 to Joseph et al., 4,532,650 to Wihl et al., 4,555,798 to Broadbent, Jr. et al., 4,556,317 to Sandland et al., 4,579,455 to Levy et al., 4,601,576 to Galbraith, 4,618,938 to Sandland et al., 4,633,504 to Wihl, 4,641,967 to Pecen, 4,644,172 to Sandland et al., 4,766,324 to Saadat et al., 4,805,123 to Speccht et al., 4,818,110 to Davidson, 4,845,558 to Tsai et al., 4,877,326 to Chadwick et al., 4,898,471 to Vaught et al., 4,926,489 to Danielson et al., 5,076,692 to Neukermans et al., 5,189,481 to Jann et al., 5,264,912 to Vaught et al., 5,355,212 to Wells et al., 5,537,669 to Evans et al., 5,563,702 to Emery et al., 5,565,979 to Gross, 5,572,598 to Wihl et al., 5,604,585 to Johnson et al., 5,737,072 to Emery et al., 5,798,829 to Vacz-Iravani, 5,822,055 to Tsai et al., 5,864,394 to Jordan, III et al., 5,883,710 to Nikoonahad et al., 5,917,588 to Addicgo, 6,020,214 ~~6,020,957~~ to Rosengaus et al., 6,052,478 to Wihl et al., 6,064,517 to Chuang et al., 6,078,386 to Tsai et al., 6,081,325 to Leslie et al., all of which are incorporated by reference as if fully set forth herein. As such, the embodiments described above may also include features of any of the systems and methods illustrated in all of the patents which have been incorporated by reference herein.